Contact Name Title - Contact Product-Env-Stewards Product-Env-Stewards Authorized Representative* Product-Env-Stewards Product	ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
Company name* Company unique ID Unique ID Authority Response Date* 2024-04-20 2024-04-20 2024-04-20 2024-04-20 Product-Env-Stewards Product-Env-S	752-21.1										als and M	fg Informati	ion		
Semilar Freduct Name Freduct Env-Stewards Phone - Contact Name Product Env-Stewards Product Env-Stewards Product Enviro Compliance NA Product-Env-Stewards @ onsemi.com Product-Env-Stewards @ onsemi.com Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards @ onsemi.com	upplier Informa	ation								·					
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Authorized Representative* Product-Env-Stewards Product Enviro Compliance Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Vanufacturing Process Information Terminal Plating / Grid Array Material Terminal Base Alloy Terminal Plating / Grid Array Material Terminal Base Alloy Matte Tin (Sn) - annealed Title - Representative* NA Product-Env-Stewards©onsemi.com Manufacturing Site Weight* UOM Unit 142.69 mg Each Max Time at Peak Temperature Number of Reflow Cycles Seconds 3 Seconds 3 Seconds 3 Seconds 1 Seconds 2 Seconds 3	ontact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product Envi-Stewards Requester Item Number Mfr Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM Unit Version Manufacturing Site Weight* UOM Unit Version Manufacturing Site Weight* Weight* Uom Unit Version Manufacturing Site Weight* Weight* Wanufacturing Process Information Vanufacturing Process Information Product-Env-Stewards@onsemi.com Manufacturing Site Weight* Uom Unit Version PH1 142.69 mg Each Vanufacturing Process Information Vanufacturing Process Information Vanufacturing Process Information Vanufacturing Process Information Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 Seconds 3	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	uthorized Represen	ntative*	Title - Representative			F	Phone - Representative*			Email - Representative*					
Manufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Product-Env-Stewar	rds		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
Anufacturing Proccess Information Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3	Requester	r Item Number	Mfr Item Number		Mfr Item Name			Effective Date	Version	. I	Manufacturing Site	1	Weight*	UOM	Unit Type
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles 260 Cu Alloy Comments			NCD5700	0DR2G	High Current IGBT	Gate Driver		2024-04-20		I	РН1	1	42.69	mg	Each
Matte Tin (Sn) - annealed CU Alloy 1 260 C 30 seconds 3 omments				erminal Race	Alloy	STD-020 MSI	Pating	Peak Proc	eess Rody 7	Cemperatur	ra May Time at Peak	Temperat	ure Numb	per of Reflow Cyc	Nec
omments				•		L Kanng						er of Kerlow Cyc	les		
	•	i (Sii) - aimealeu	C	O Anoy	1			200		IC	50	secon	us 3		
ver 1 - maximum time at peak temperature during soldering is 10-50 seconds		me at week townswature	a dunina aal	domina ia 10 3	20 sacands										
or more information regarding material composition please refer to page 3															

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of					
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.73	mg	Supplier	Silicon (Si)	7440-21-3		2.73	mg
Die Attach	4.85	mg	Supplier	Silver (Ag)	7440-22-4		3.6375	mg
			Supplier	Epoxy resins	129915-35-1		1.2125	mg
Lead Frame	75.92	mg	Supplier	Silver (Ag)	7440-22-4		0.7592	mg
			Supplier	Zinc (Zn)	7440-66-6		0.1518	mg
			Supplier	Iron (Fe)	7439-89-6		1.9739	mg
			Supplier	Copper (Cu)	7440-50-8		73.035	mg
Mold Compound-Black	55.11	mg		Epoxy Phenol Resin	proprietary data		5.7866	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		49.3234	mg
Plating	3.73	mg	Supplier	Tin (Sn)	7440-31-5		3.73	mg
Wire Bond - Au	0.35	mg	Supplier	Gold (Au)	7440-57-5		0.35	mg